Vincotech

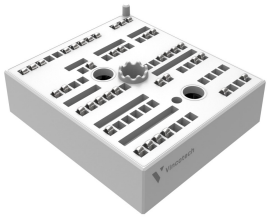
V23990-K359-F40-PM
datasheet

MiniSKiiP PACK 2 **1200 V / 50 A**

Features

- Three-phase inverter

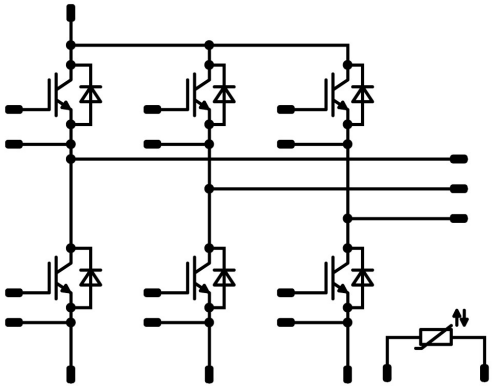
MiniSkiip 2 housing



Target applications

- Embedded Drives
- Industrial Drives

Schematic



Types

- V23990-K359-F40-PM

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C	$T_j = T_{jmax}$ T_s = 80 °C	60	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	150	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	163	W
Gate-emitter voltage	V_{GES}		±20	V
Short circuit ratings	t_{SC}	V_{GE} = 15 V V_{cc} = 800 V T_j = 150 °C	10	µs
Maximum junction temperature	T_{jmax}		175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F	T_j = T_{jmax} T_s = 80 °C	54	A
Surge (non-repetitive) forward current	I_{FSM}	50 Hz Single Half Sine Wave t_p = 10 ms T_j = 150 °C	270	A
Total power dissipation	P_{tot}	T_j = T_{jmax} T_s = 80 °C	123	W
Maximum junction temperature	T_{jmax}		175	°C
Module Properties				
Thermal Properties				
Storage temperature	T_{stg}		-40…+125	°C
Operation temperature under switching condition	T_{jop}		-40…(T_{jmax} - 25)	°C
Isolation Properties				
Isolation voltage	V_{isol}	DC Test Voltage* t_p = 2 s	5500	V
		AC Voltage t_p = 1 min	2500	V
Creepage distance		With std lid For more informations see handling instructions	6,3	mm
Clearance		With std lid For more informations see handling instructions	6,3	mm
Comparative Tracking Index	CTI		> 200	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}$			0,0017	25	5,3	5,8	6,3	V
Collector-emitter saturation voltage	V_{CEsat}		15		50	25 150	1,58	1,92 2,33	2,2	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			61	µA
Gate-emitter leakage current	I_{GES}		20	0		25			200	nA
Internal gate resistance	r_g							4		Ω
Input capacitance	C_{ies}	f= 1 Mhz	0	25		25		2800		pF
Reverse transfer capacitance	C_{res}							100		
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 2,5 W/mK (HPTP)						0,58		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 8 Ω R_{goff} = 8 Ω	±15	600	50	25 150		101 106		ns
Rise time	t_r					25 150		19 25		
Turn-off delay time	$t_{d(off)}$					25 150		224 296		
Fall time	t_f					25 150		89 116		
Turn-on energy (per pulse)	E_{on}	Q_{rFWD} = 3,2 µC Q_{rFWD} = 8,7 µC				25 150		2,64 4,62		mWs
Turn-off energy (per pulse)	E_{off}					25 150		2,89 4,75		

Characteristic Values

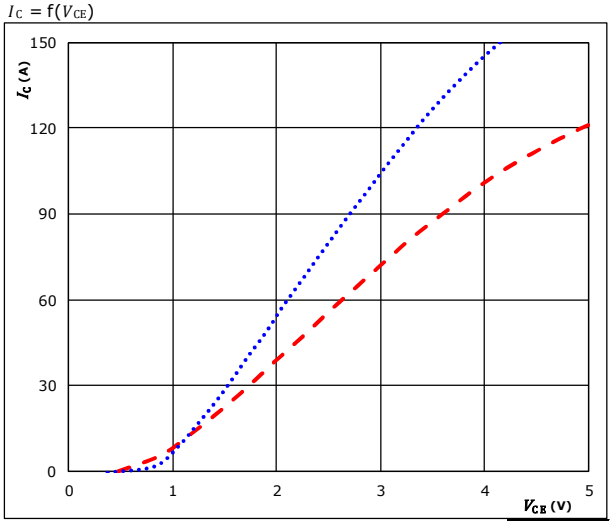
Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				50	25 150		2,20 2,20	2,6	V
Reverse leakage current	I_R			1200		25 150			60 8800	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 2,5 W/mK (HPTP)						0,77		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt = 3197 A/µs di/dt = 2339 A/µs	±15	600	50	25 150		53,6 67		A
Reverse recovery time	t_{rr}					25 150		121 294		ns
Recovered charge	Q_r					25 150		3,25 8,66		µC
Reverse recovered energy	E_{rec}					25 150		1,12 3,35		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 150		2708 467		A/µs
Thermistor										
Rated resistance	R					25		1		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 1670 Ω				100	-2		+2	%
R_{100}	R					100		1670		Ω
Power dissipation constant						25		0,76		mW/K
A-value	$A_{(25/50)}$					25		$7,635*10^{-3}$		1/K
B-value	$B_{(25/100)}$					25		$1,731*10^{-5}$		1/K²
Vincotech PTC Reference									E	

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

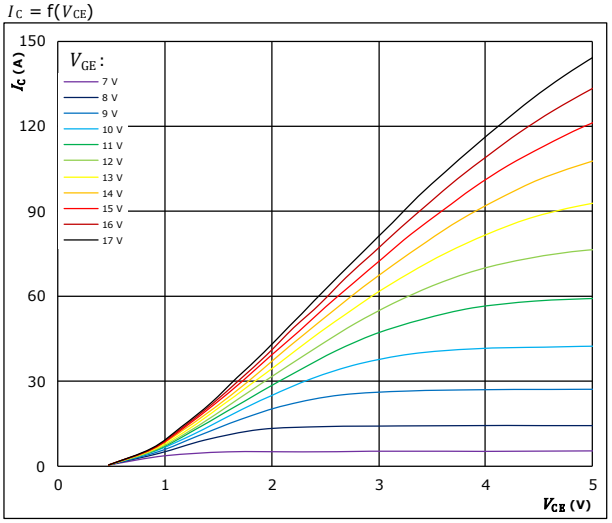


t_p =	250	µs	T_j:	25 °C	·····
V_{GE} =	15	V		150 °C	– – –

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

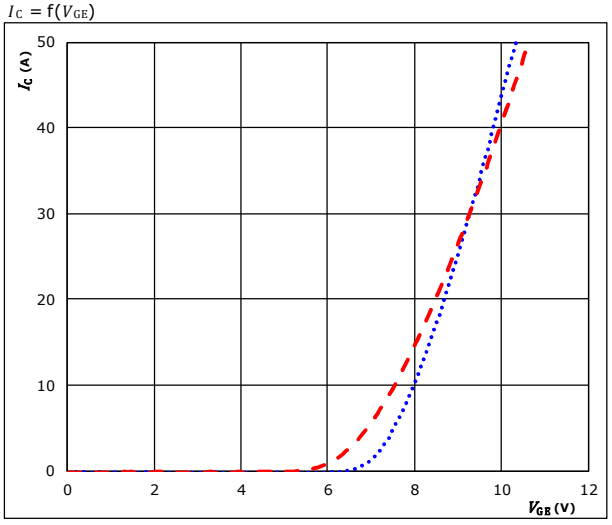


t_p =	250	µs
T_j =	150	°C
V_{GE} from	7 V to 17 V in steps of 1 V	

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

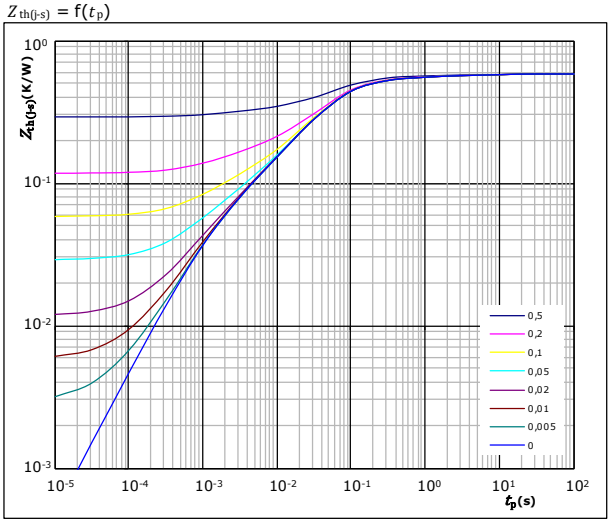


t_p =	100	µs	T_j:	25 °C	·····
V_{CE} =	10	V		150 °C	– – –

figure 4. **IGBT**

Transient thermal impedance as function of pulse duration

$Z_{th(j-s)} = f(t_p)$



D =	t_p / T	
$R_{th(j-s)}$ =	0,58	K/W

IGBT thermal model values

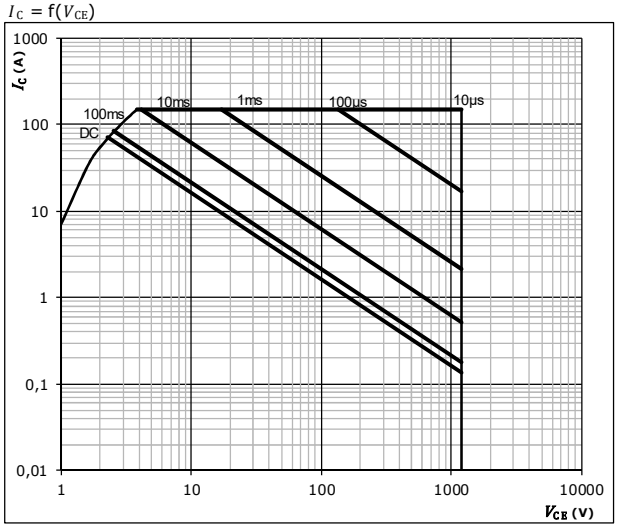
R (K/W)	τ (s)
2,17E-02	4,34E+00
4,06E-02	3,69E-01
1,08E-01	6,60E-02
3,12E-01	2,21E-02
5,81E-02	4,29E-03
3,90E-02	6,58E-04
2,69E-03	3,18E-04

Inverter Switch Characteristics

figure 5. **IGBT**

Safe operating area

$I_C = f(V_{CE})$



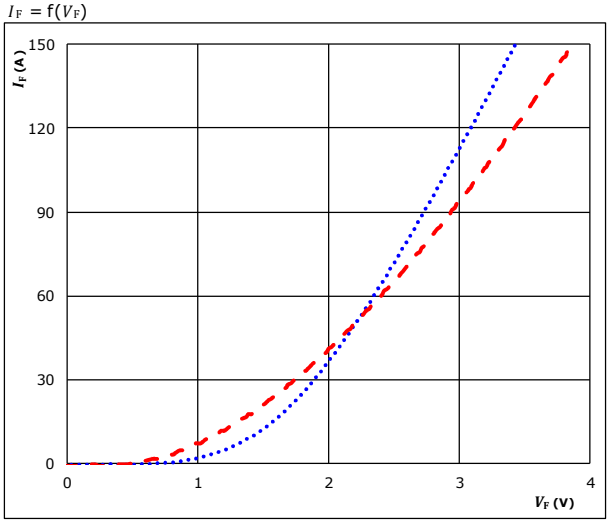
D =	single pulse	
T_s =	80	ºC
V_{GE} =	±15	V
T_j =	T_{jmax}	

Inverter Diode Characteristics

figure 1. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



t_p = 250 µs

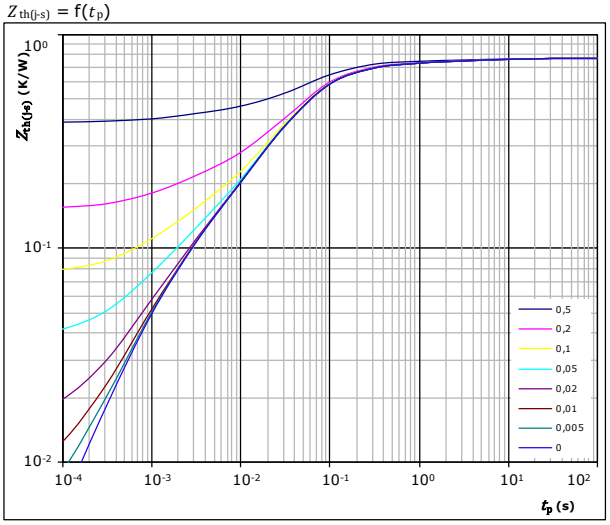
T_j: 25 °C

150 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 0,77 K/W

FWD thermal model values

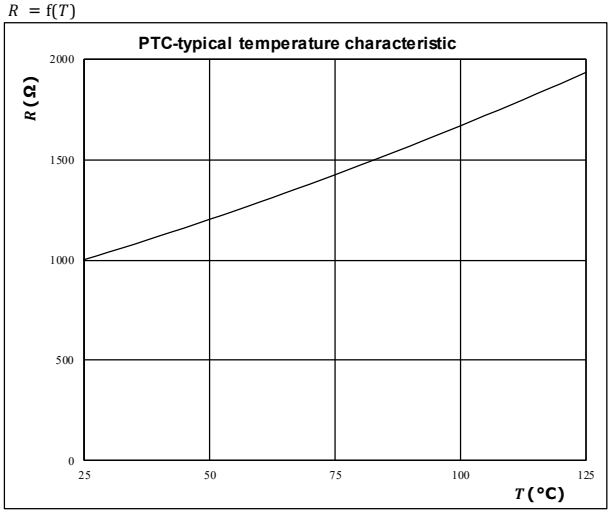
R (K/W)	τ (s)
2,87E-02	5,74E+00
5,37E-02	4,89E-01
1,43E-01	8,73E-02
4,13E-01	2,92E-02
7,69E-02	5,67E-03
5,16E-02	8,71E-04
3,56E-03	4,21E-04

Thermistor Characteristics

figure 1. **Thermistor**

Typical PTC characteristic
as a function of temperature

$R = f(T)$

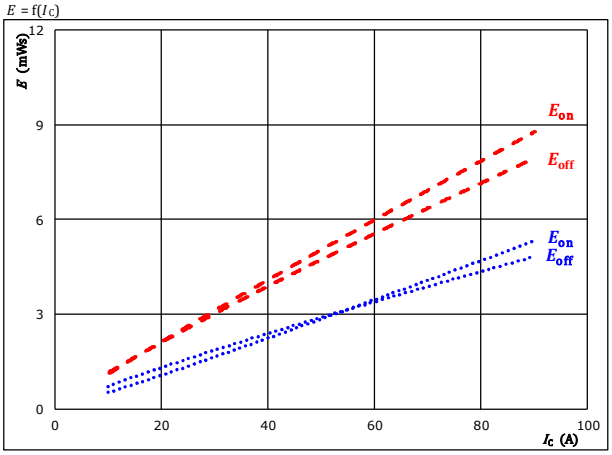


Inverter Switching Characteristics

figure 1. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



With an inductive load at

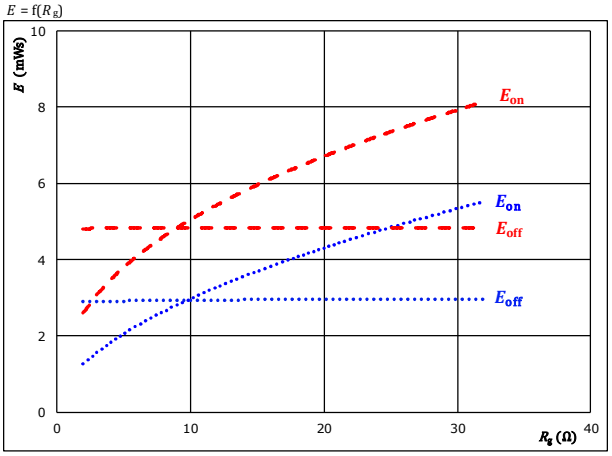
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	8	Ω
R_{goff} =	8	Ω

T_j: 25 °C, 150 °C

figure 2. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



With an inductive load at

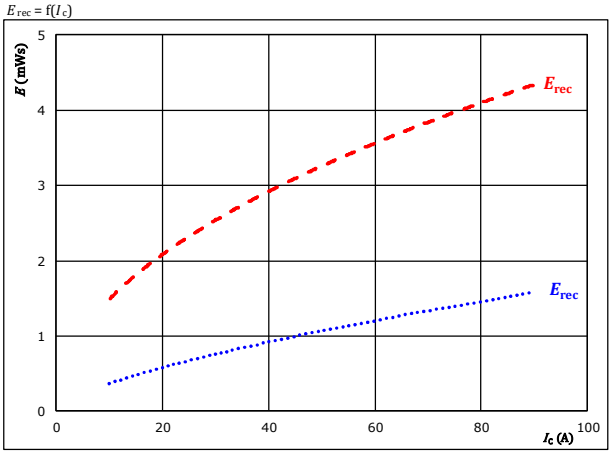
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	50	A

T_j: 25 °C, 150 °C

figure 3. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



With an inductive load at

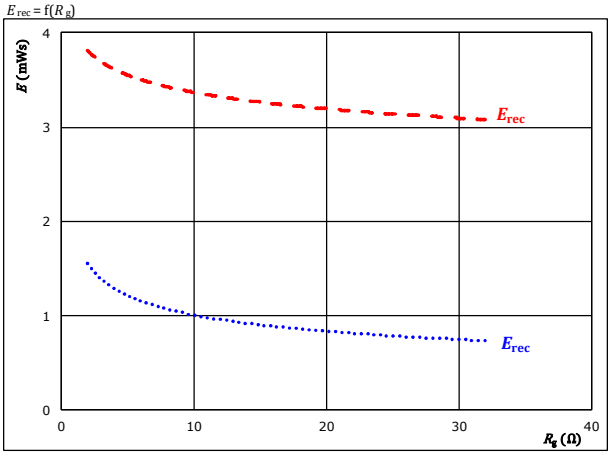
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	8	Ω

T_j: 25 °C, 150 °C

figure 4. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	50	A

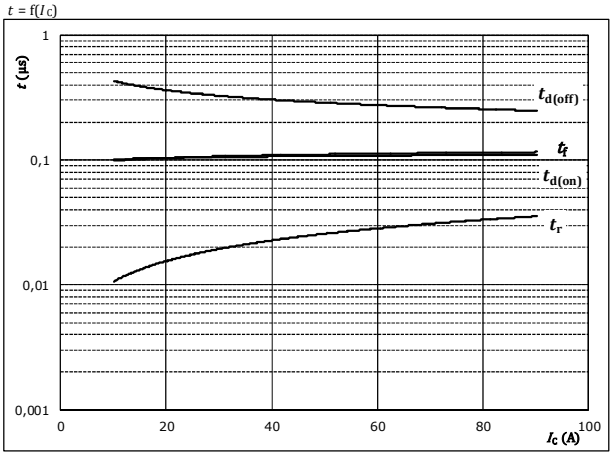
T_j: 25 °C, 150 °C

Inverter Switching Characteristics

figure 5. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



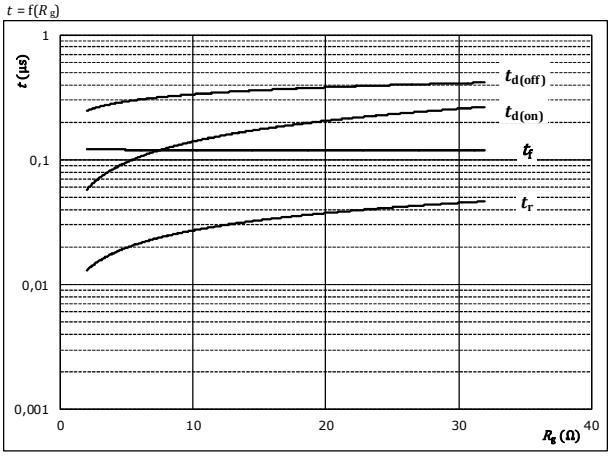
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	8	Ω
R_{goff} =	8	Ω

figure 6. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



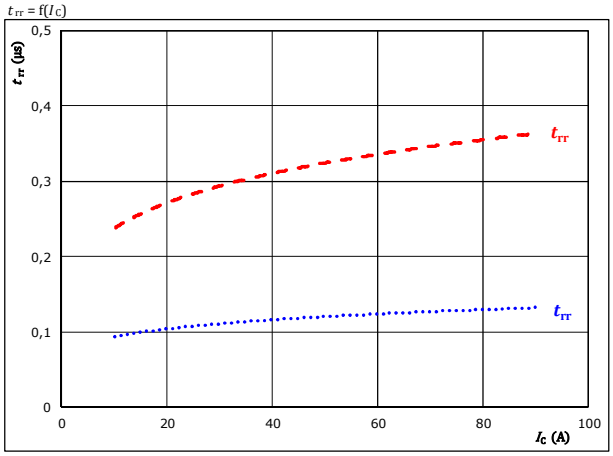
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	50	A

figure 7. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



With an inductive load at

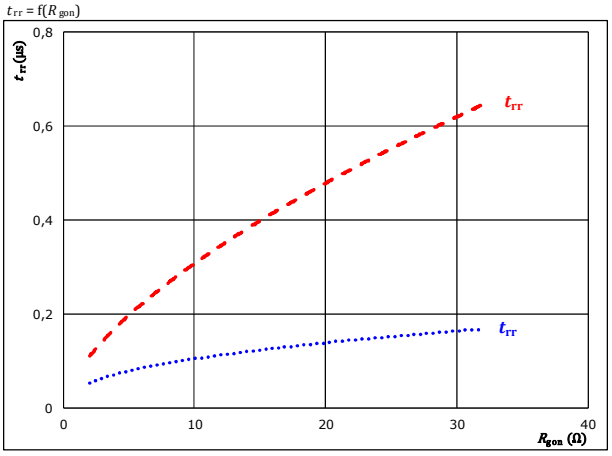
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	8	Ω

T_j: 25 °C, 150 °C

figure 8. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



With an inductive load at

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	50	A

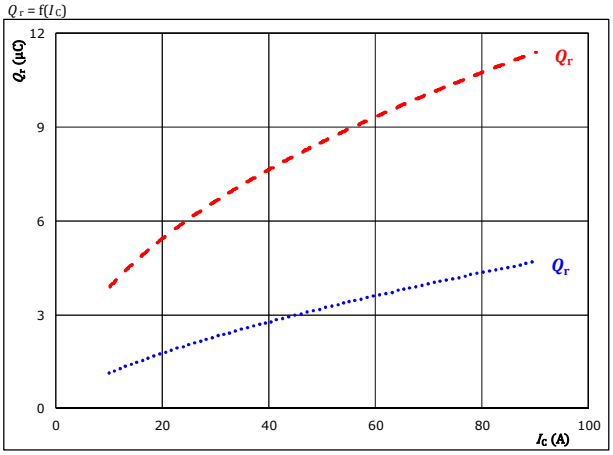
T_j: 25 °C, 150 °C

Inverter Switching Characteristics

figure 9. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$



With an inductive load at

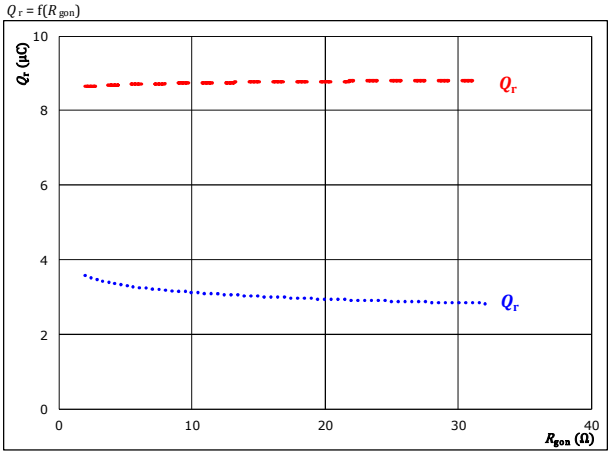
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	8	Ω

T_j: 25 °C, 150 °C

figure 10. **FWD**

Typical recovered charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$



With an inductive load at

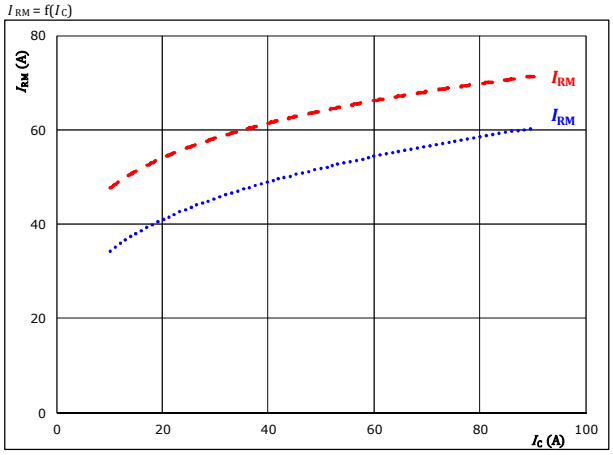
V_{CE}=	600	V
V_{GE} =	±15	V
I_C=	50	A

T_j: 25 °C, 150 °C

figure 11. **FWD**

Typical peak reverse recovery current current as a function of collector current

$I_{RM} = f(I_C)$



With an inductive load at

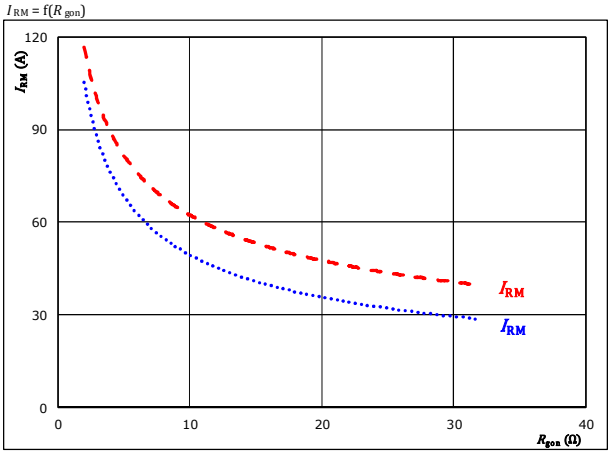
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	8	Ω

T_j: 25 °C, 150 °C

figure 12. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



With an inductive load at

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	50	A

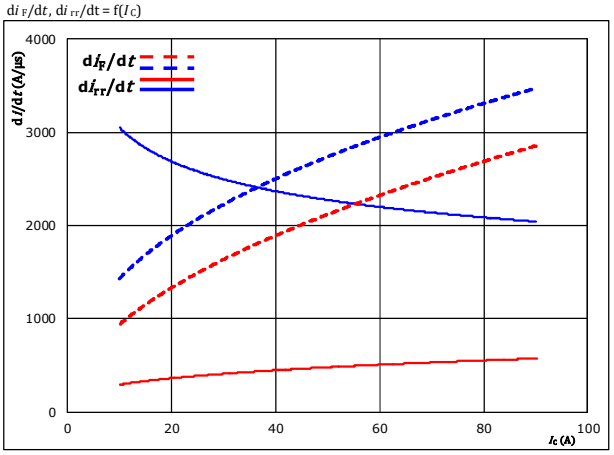
T_j: 25 °C, 150 °C

Inverter Switching Characteristics

figure 13. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, $di_{rr}/dt = f(I_C)$



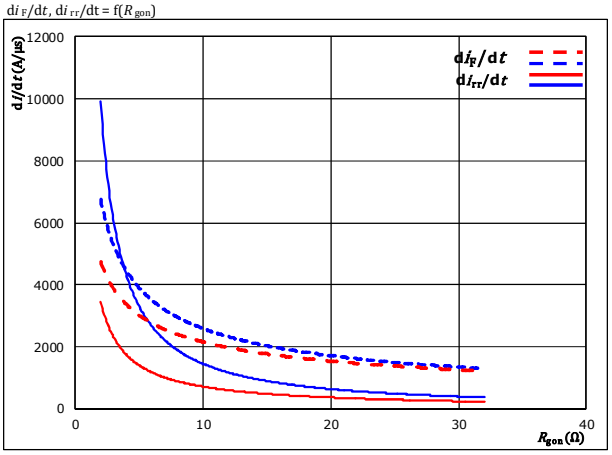
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		150 °C
R_{gon} =	8	Ω		

figure 14. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

di_F/dt, $di_{rr}/dt = f(R_{gon})$



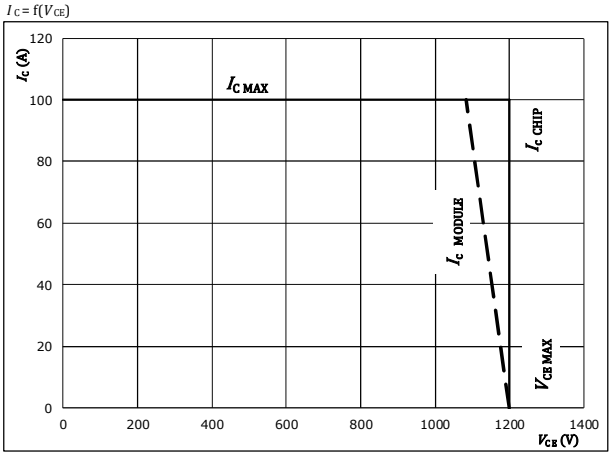
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		150 °C
I_C =	50	A		

figure 15. **IGBT**

Reverse bias safe operating area

$I_C = f(V_{CE})$



At

T_j =	150	°C
R_{gon} =	8	Ω
R_{goff} =	8	Ω

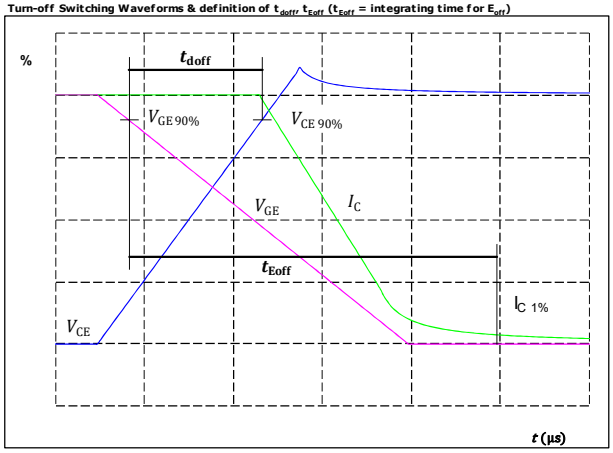
Inverter Switching Definitions

General conditions

T_j	=	125 °C
R_{gon}	=	8 Ω
R_{goff}	=	8 Ω

figure 1. IGBT

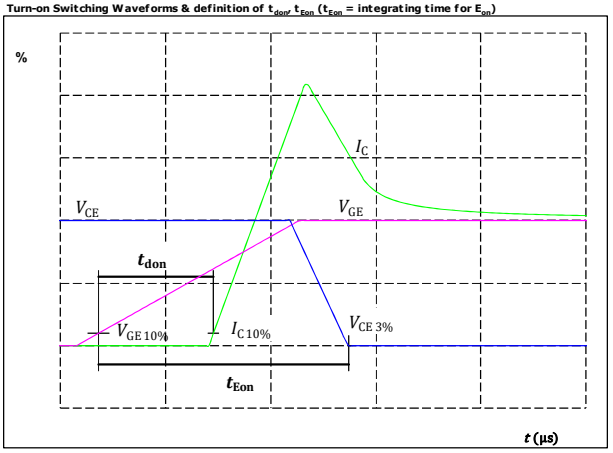
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	50	A
t_{doff} =	296	ns

figure 2. IGBT

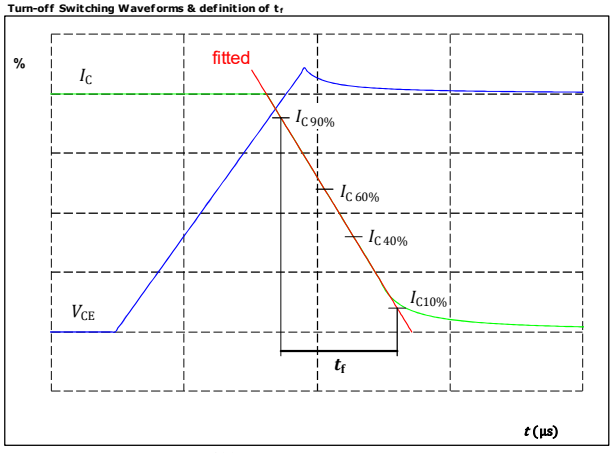
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	50	A
t_{don} =	106	ns

figure 3. IGBT

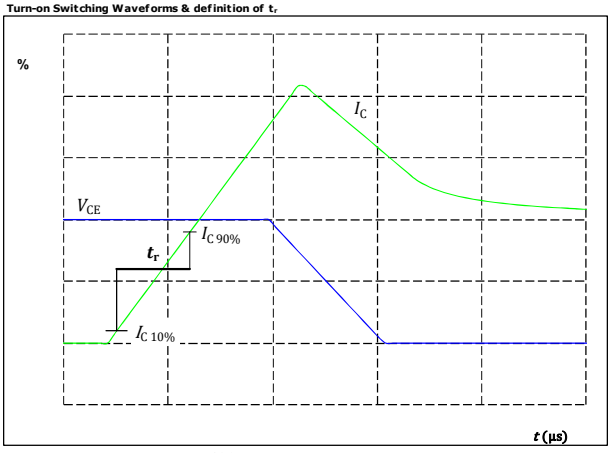
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	50	A
t_f =	116	ns

figure 4. IGBT

Turn-on Switching Waveforms & definition of t_r

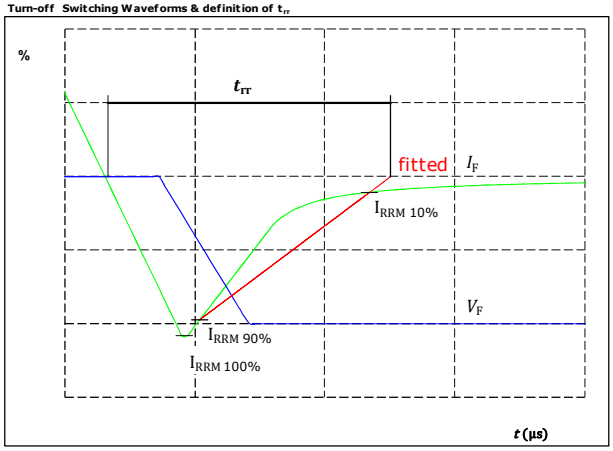


$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	50	A
t_r =	25	ns

Inverter Switching Characteristics

figure 5. **FWD**

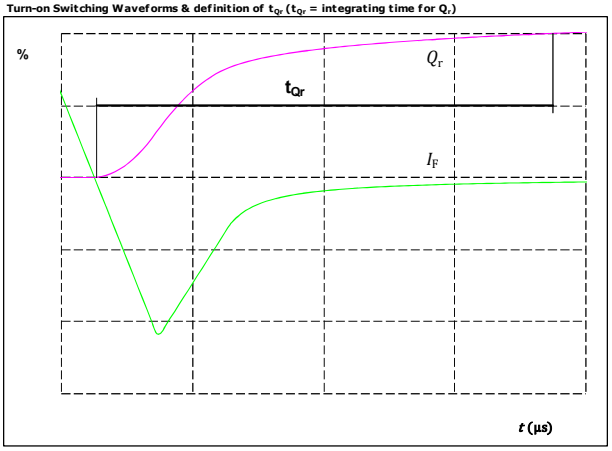
Turn-off Switching Waveforms & definition of t_{rr}



$V_F(100\%)$ =	600	V
$I_F(100\%)$ =	50	A
$I_{RRM}(100\%)$ =	67	A
t_{rr} =	294	ns

figure 6. **FWD**

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



$I_F(100\%)$ =	50	A
$Q_r(100\%)$ =	8,66	µC

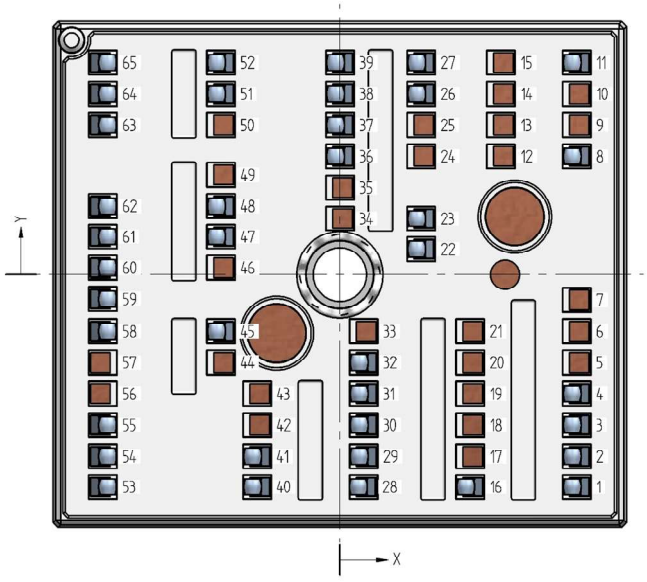
Ordering Code & Marking

Version	Ordering Code
With std lid (6.5mm height) + no thermal grease	V23990-K359-F40-/0A/ -PM
With thin lid (2.8mm height) + no thermal grease	V23990-K359-F40-/0B/ -PM
With std lid (6.5mm height) + thermal grease (0,8 W/mK, P12, silicone-based)	V23990-K359-F40-/1A/ -PM
With thin lid (2.8mm height) + thermal grease (0,8 W/mK, P12, silicone-based)	V23990-K359-F40-/1B/ -PM
With std lid (6.5mm height) + thermal grease (2,5 W/mK, TG20032, silicone-free)	V23990-K359-F40-/4A/ -PM
With thin lid (2.8mm height) + thermal grease (2,5 W/mK, TG20032, silicone-free)	V23990-K359-F40-/4B/ -PM
With std lid (6.5mm height) + thermal grease (2,5 W/mK, HPTP, silicone-based)	V23990-K359-F40-/5A/ -PM
With thin lid (2.8mm height) + thermal grease (2,5 W/mK, HPTP, silicone-based)	V23990-K359-F40-/5B/ -PM

Text	**VIN**	**Date code**	**Name&Ver**	**UL**	**Lot**	**Serial**
	VIN	WWYY	NNNNNNNVV	UL	LLLLL	SSSS
Datamatrix	**Type&Ver**	**Lot number**	**Serial**	**Date code**		
	TTTTTTVV	LLLLL	SSSS	WWYY		

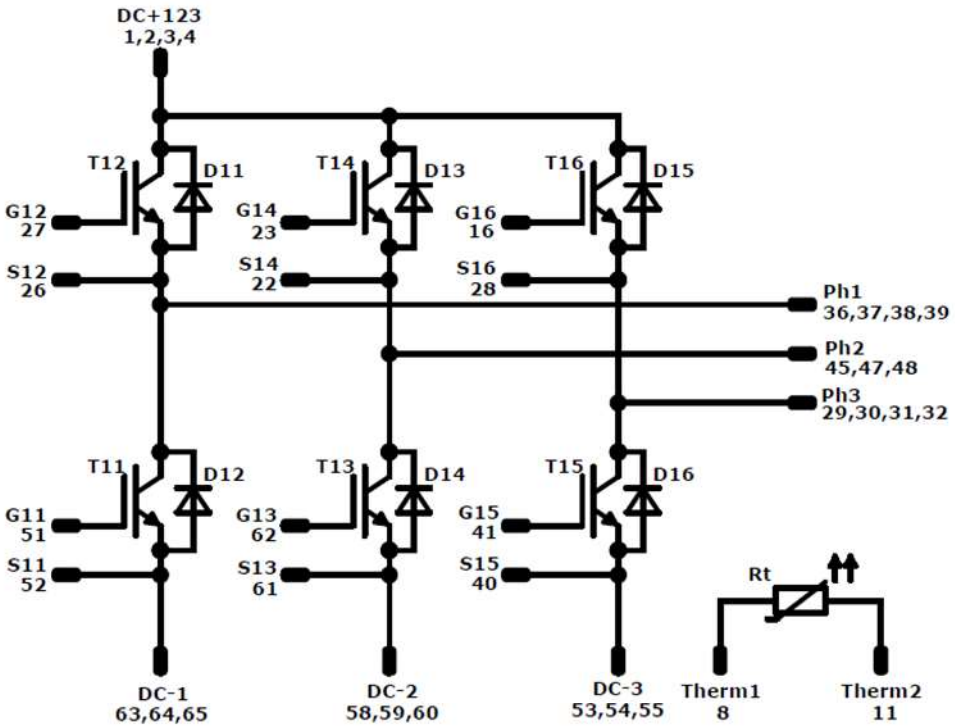
Outline

PCB pad table				PCB pad table			
Pin	X	Y	Function	Pin	X	Y	Function
1	24,38	-21,8	DC+123	48	-12,22	7,1	Ph2
2	24,38	-18,6	DC+123	49	Not assembled		
3	24,38	-15,4	DC+123	50	Not assembled		
4	24,38	-12,2	DC+123	51	-12,22	18,6	G11
5	Not assembled			52	-12,22	21,8	S11
6	Not assembled			53	-24,38	-21,8	DC-3
7	Not assembled			54	-24,38	-18,6	DC-3
8	24,38	12,2	Therm1	55	-24,38	-15,4	DC-3
9	Not assembled			56	Not assembled		
10	Not assembled			57	Not assembled		
11	24,38	21,8	Therm2	58	-24,38	-5,8	DC-2
12	Not assembled			59	-24,38	-2,5	DC-2
13	Not assembled			60	-24,38	0,7	DC-2
14	Not assembled			61	-24,38	3,9	S13
15	Not assembled			62	-24,38	7,1	G13
16	13,42	-21,8	G16	63	-24,38	15,4	DC-1
17	Not assembled			64	-24,38	18,6	DC-1
18	Not assembled			65	-24,38	21,8	DC-1
19	Not assembled						
20	Not assembled						
21	Not assembled						
22	8,38	2,6	S14				
23	8,38	5,8	G14				
24	Not assembled						
25	Not assembled						
26	8,38	18,6	S12				
27	8,38	21,8	G12				
28	2,38	-21,8	S16				
29	2,46	-18,6	Ph3				
30	2,46	-15,4	Ph3				
31	2,46	-12,2	Ph3				
32	2,46	-9	Ph3				
33	Not assembled						
34	Not assembled						
35	Not assembled						
36	0,03	12,2	Ph1				
37	0,03	15,4	Ph1				
38	0,03	18,6	Ph1				
39	0,03	21,8	Ph1				
40	-8,5	-21,8	S15				
41	-8,5	-18,6	G15				
42	Not assembled						
43	Not assembled						
44	Not assembled						
45	-12,22	-5,8	Ph2				
46	Not assembled						
47	-12,22	3,9	Ph2				



Pad positions refers to center point. For more informations on pad design please see package data

Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T11, T12, T13, T14, T15, T16	IGBT	1200 V	50 A	Inverter Switch	
D11, D12, D13, D14, D15, D16	FWD	1200 V	50 A	Inverter Diode	
Rt	PTC			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 72	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for MiniSkiiP® 2 packages see vincotech.com website.

Package data
Package data for MiniSkiiP® 2 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
V23990-K359-F40-D2k1-14	19 Feb. 2019		

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